

Application Serial No. 10/649,577  
Attorney Docket No.: 0140153

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**In the Claims:**

**Claim 1 (previously presented):** A method for forming a package for an electrical device, said method comprising the steps of:

- attaching a removable material to a surface of a conductive material, wherein said removable material comprises a soluble adhesive;
- forming isolated conductive features within said conductive material;
- attaching encapsulant to said isolated conductive features and said removable material; and
- removing said removable material from said conductive features and said encapsulant.

**Claim 2 (original):** The method for forming a package for the electronic device of claim 1, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.

**Claim 3 (original):** The method for forming a package for the electronic device of claim 1, further comprising the step of forming a die attach pad within said conductive material.

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**Claim 4 (previously presented):** The method for forming a package for the electronic device of claim 1, further comprising the step of coupling the device to said die attach pad.

**Claim 5 (original):** The method for forming a package for an electronic device of claim 1, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.

**Claim 6 (original):** The method for forming a package for the electronic device of claim 1, further comprising the step of singulating individual packaged devices.

**Claim 7 (original):** The method of claim 1, wherein the removable material is water soluble adhesive.

**Claim 8 (original):** The method of claim 7, wherein the removable material is removed with deionized water.

**Claims 9-15 (cancelled).**

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**Claim 16 (previously presented):** The method of claim 1, wherein the removable material is mold stencil that is used in said attaching encapsulant step.

**Claim 17 (previously presented):** The method of claim 1, wherein the removable material comprises a polyimide material and a water soluble adhesive.

**Claims 18-19 (cancelled).**

**Claim 20 (previously presented):** The method of claim 1, wherein said conductive material comprises a metal frame.

**Claim 21 (previously presented):** The method of claim 20, wherein the metal frame comprises a leadframe.

**Claim 22 (previously presented):** The method of claim 21, further comprising the step of forming a die attach pad within said conductive materials, wherein said die attach pad is not offset from said isolated conductive features.

**Claim 23 (previously presented):** The method of claim 21, wherein a single row of connectors is formed around a perimeter of said leadframe.

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**Claim 24 (previously presented):** The method of claim 20, wherein said metal frame comprises a metal sheet.

**Claim 25 (previously presented):** The method of claim 24, wherein multiple rows of connectors are formed around a perimeter of the metal sheet.

**Claim 26 (previously presented):** The method of claim 20, wherein the removable material covers substantially the entire bottom surface of said metal frame.

**Claim 27 (previously presented):** The method of claim 4, wherein the electronic device is coupled to said die attach pad via conductive epoxy.

**Claim 28 (previously presented):** A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material before one or more isolated conductive features have been formed within said conductive material, wherein said removable material comprises a soluble adhesive;

forming said isolated conductive features within said conductive material;

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attaching encapsulant to said isolated conductive features and said removable material, wherein said attaching step is performed before a singulation process is performed to separate said package; and

removing said removable material from said conductive features and said encapsulant, wherein the removing said material step is performed after the singulation process is performed to separate said package.